



JOC827X Series

Rev.A.1.0

The products are transistor opto-couplers in a plastic DIP8 package with different lead forming options

1 s pulse

AC for 1minute, R.H.=40~60%

(Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	$I_F=10\text{mA}$	-	1.2	1.5	V
	Reverse Current	I_R	$V_R=6\text{V}$	-	-	1	A
	Terminal Capacitance	C_t	$V=0$, $f=1\text{MHz}$	-	30	250	pF
Output	Collector-Emitter dark current	I_{CEO}	$V_{CE}=20\text{V}$, $I_F=0$	-	-	50	nA
	Collector-Emitter breakdown voltage	BV_{CEO}	$I_C=0.1\text{mA}$ $I_F=0$	80	-	-	V
	Emitter-Collector breakdown voltage	BV_{ECO}	$I_E=0.1\text{mA}$ $I_F=0$	6	-	-	V
	Current transfer ratio	CTR	$I_F=5\text{mA}$ $V_{CE}=5\text{V}$	80	-	600	%
	Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_F=2$				

Transfer
Characteristics

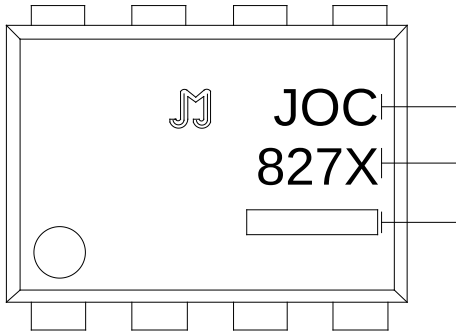
		: Company Abbr. : Part Number & Rank : Production Information Code	
DIP	50 Units/Tube	40 Tubes/Inner box	5 Inner box/Outer box =10k Units
SMD	1200 Units/Reel	2 Reels/Inner box	5 Inner box/Outer box =12k Units

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

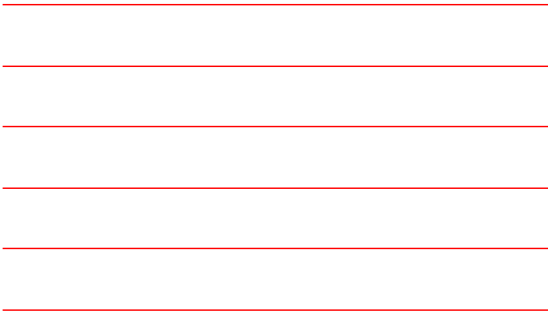


FIG.2: Collector Power Dissipation vs. Ambient Temperature

FIG.7: Normalized Current Transfer Ratio vs. Ambient Temperature

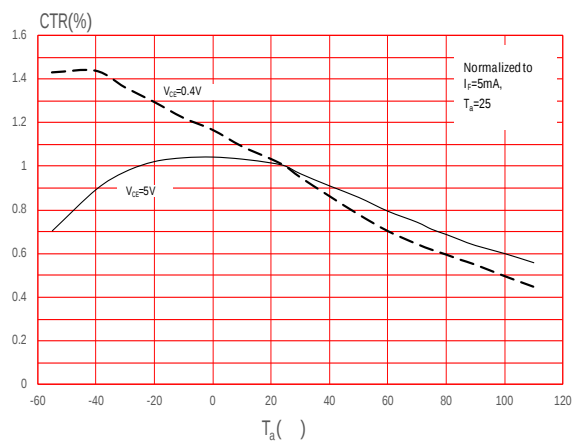


FIG.8: Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature

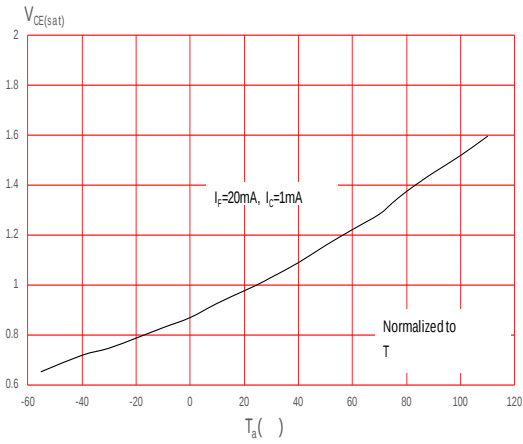


FIG.11: Test Circuits of Response Time

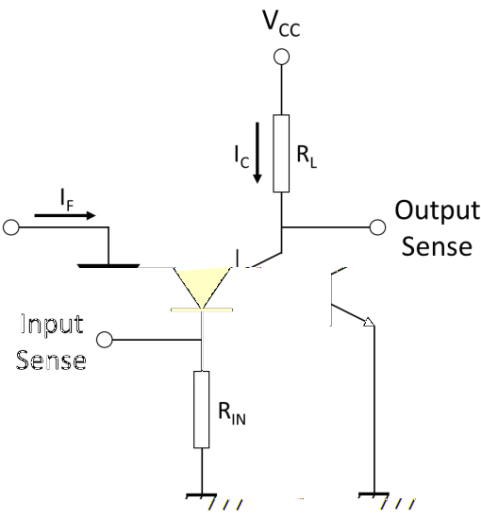


FIG.12: Curves of Response Time

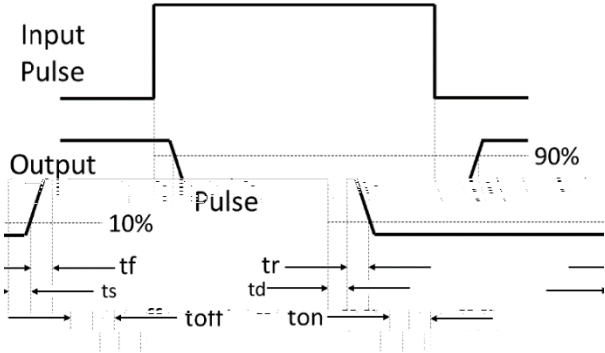
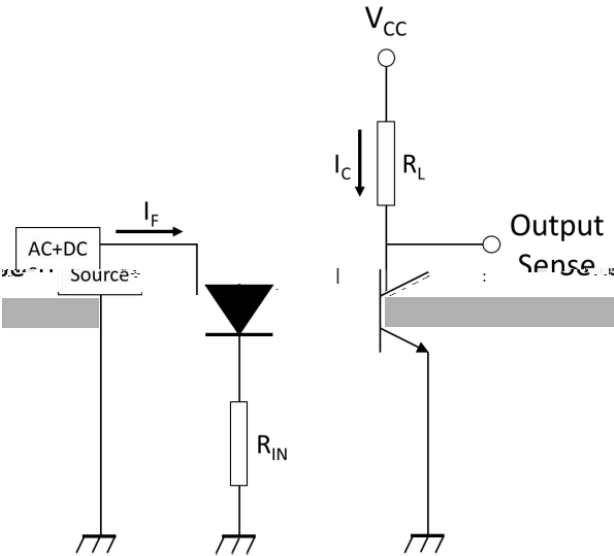
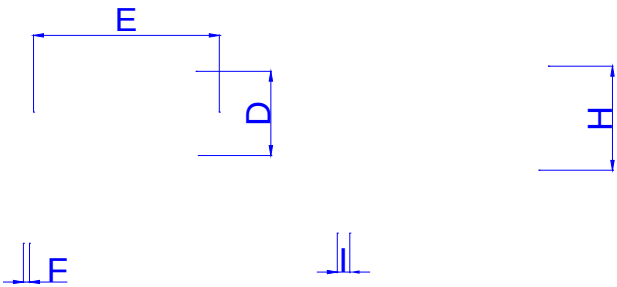


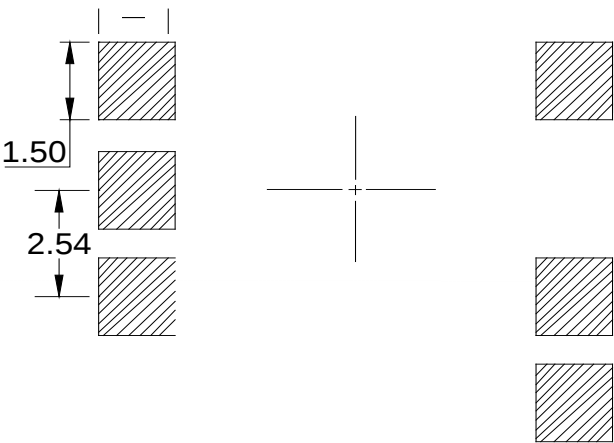
FIG.13: Test Circuits of Frequency Response



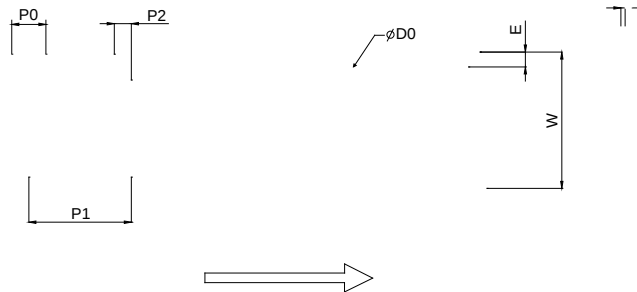
Standard DIP Type:



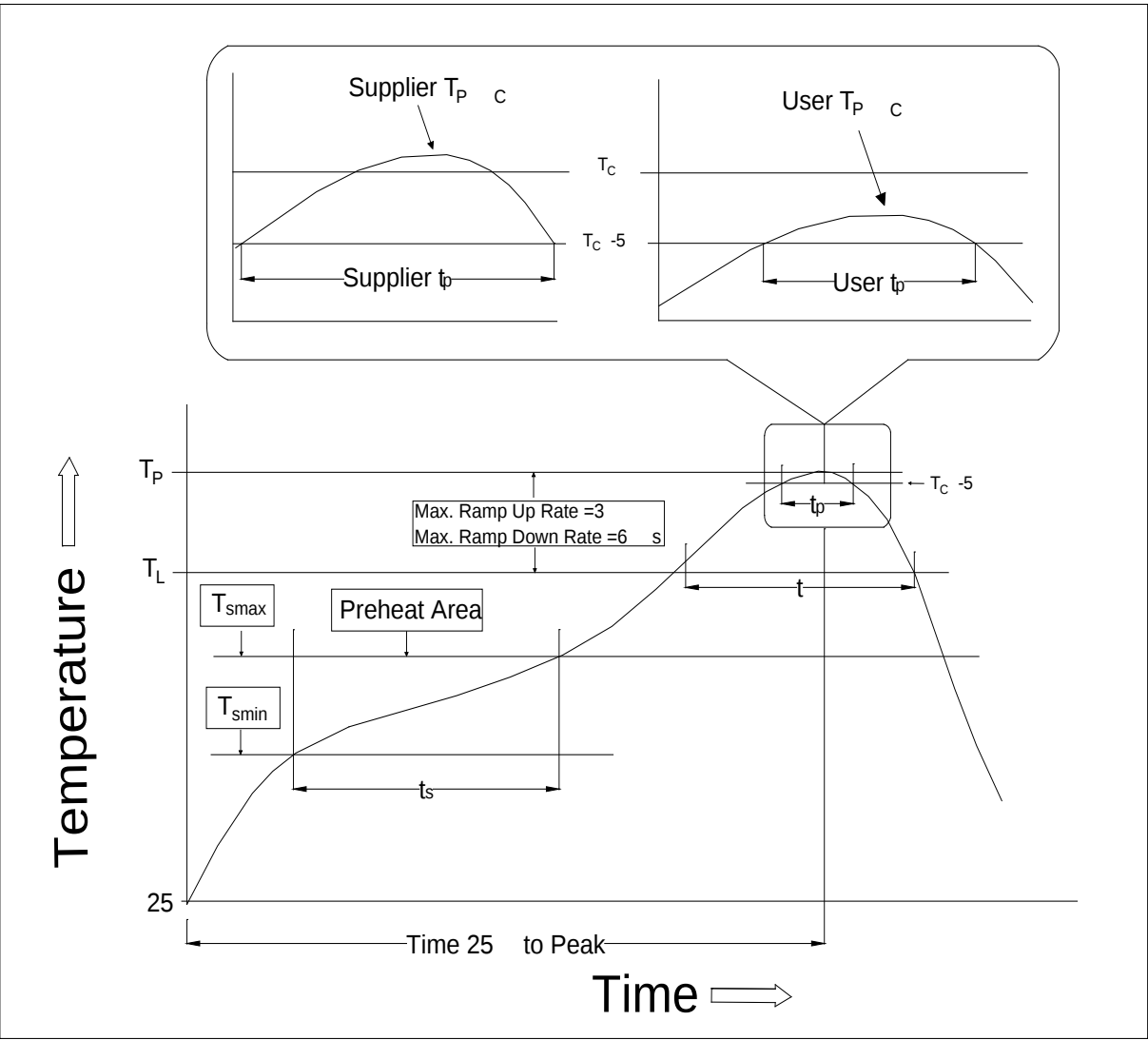
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92			
F	0.15		0.35			
G	0.90		1.50			
H	3.90		4.50			
I	0.40		0.60			
J						



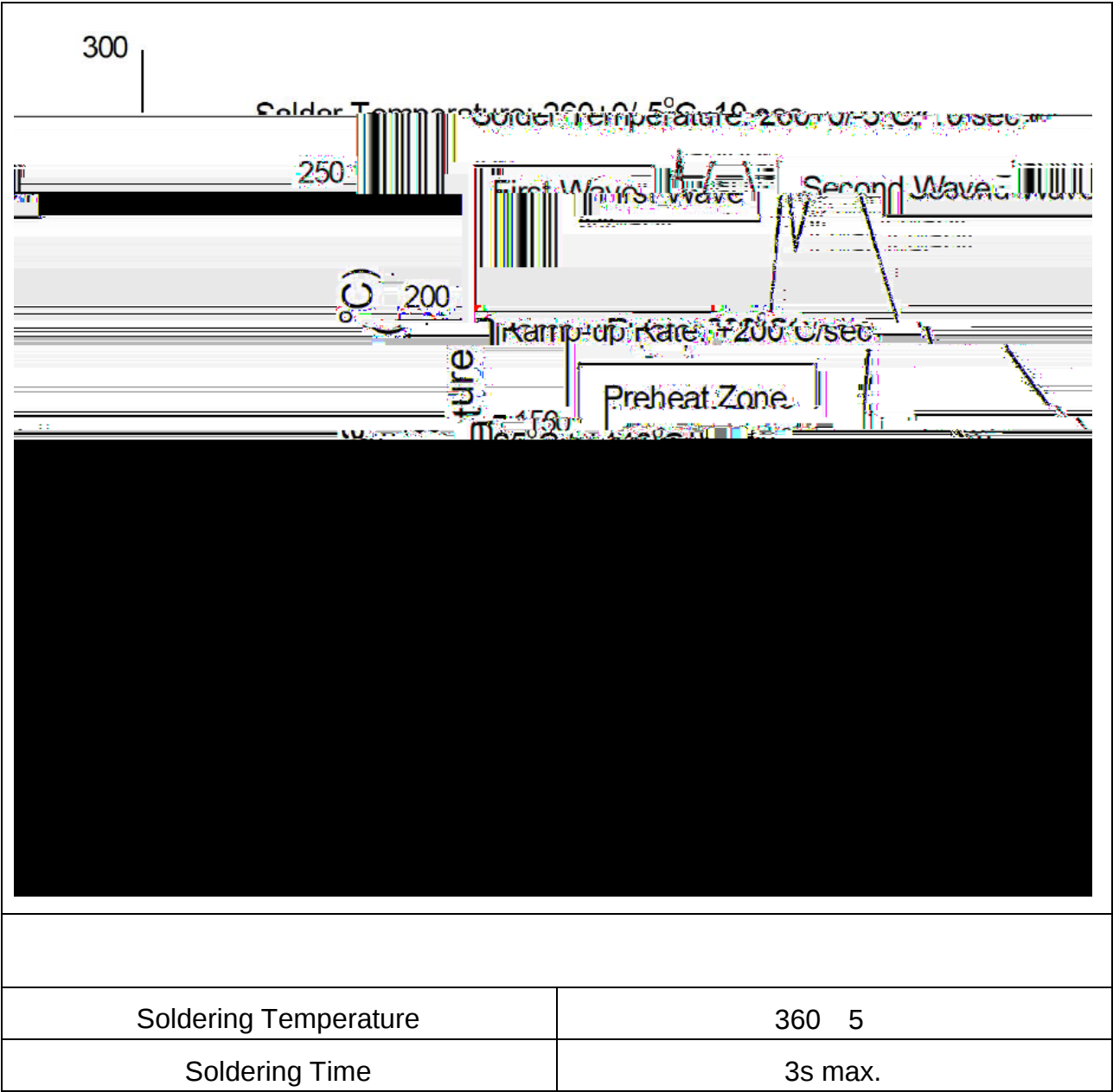
tion T3



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T_{smin})	100	150
Temperature Max. (T_{smax})	150	200
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t_L to t_P)	3 $^{\circ}\text{C}/\text{second}$ max.	3 $^{\circ}\text{C}/\text{second}$ max.
Liquidus Temperature (T_L)	183	217
Time (t_L) Maintained Above (T_L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 ± 0 ± 5	260 ± 0 ± 5
Time (t_P) within 5 $^{\circ}\text{C}$ of 260	10 seconds	10 seconds
Ramp-down Rate (T_P to T_L)	3-6 $^{\circ}\text{C}/\text{second}$	3-6 $^{\circ}\text{C}/\text{second}$
Time 25 $^{\circ}\text{C}$ to Peak Temperature	6 minutes max.	8 minutes max.



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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